

# **General Description**

DA9353 is a high voltage, bi-directional multi-input capacitive current and voltage multiplier suitable for applications supplied by 20 V wireless input, 20 V wireless input +1 V modulation, or any USB input voltage between 4 V and 21 V in current multiplier (voltage divider) configuration. In capacitive voltage multiplier (current divider) configuration, input is supported by a dual (2S) Li-lon or Li-Polymer battery pack or any input voltage between 3.5 V and 12 V.

The power voltage converter (PVC) operates with conversion efficiency exceeding 98 %. Low profile external components and a minimum PCB footprint allow small circuit implementation in compact applications. As the pass devices are fully integrated, no external power switches are needed. Power conversion and the operational modes are controlled via an I<sup>2</sup>C compatible interface.

DA9353 supports voltage detection with autonomous wake-up and programmable soft-start to limit inrush current from the power node. It also implements integrated over-temperature and over-current protection for increased system reliability without the need for external sensing components.

Enable supervision and nIRQ signals are available, supporting different power up or power cycle scenarios.

# **Key Features**

- Input voltage V<sub>V2X</sub> (Forward mode) 4 V to 21 V
- Input voltage V<sub>V1X</sub> (Reverse mode) 3.5 V to 12 V
- Output voltage  $V_{V1X} = \frac{1}{2} * V_{V2X}$  (Forward mode)
- Output voltage
   V<sub>V2X</sub> = 2 \* V<sub>V1X</sub> (Reverse mode)
- 4.5 A output current (Divide mode)
- 3 A output current (Bypass mode)
- 2 A output current (Multiply mode)
- Typical 30 µA quiescent current (POWERDOWN)

- Multi-input power muxing capability
- Integrated power switches
- Autonomous soft start
- Automatic on/off bypass power switch (VPSOUT), VBUS2, and V2X
- ENB pin to control PVC operation
- I<sup>2</sup>C compatible control interface
- Voltage, current, and temperature supervision
- -40 °C to +125 °C junction temperature range
- 54 ball WLCSP 3.27 mm x 2.82 mm (0.40 mm pitch) middle three rows staggered bumps
- 1 mm max. external components height

# **Applications**

- Smartphones
- Tablets
- Notebook computers
- DSLR and mirrorless cameras
- VR / AR Headsets
- Game consoles
- Drones
- Other 1S or 2S battery powered applications



# **System Diagram**

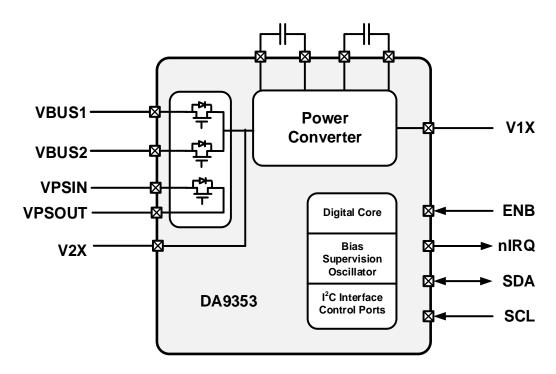


Figure 1: System Diagram



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### 1 Terms and Definitions

FSM Finite-state machine

HV High voltage Li-lon Lithium-ion

nIRQ Active low interrupt request

OTG On-the-go

OTP One-time programmable memory

OVP Over voltage protection
PCB Printed circuit board
PD Power delivery

PPS Programmable power supply
PVC Power voltage converter
QVBUS1 Power mux on VBUS1
QVBUS2 Power mux on VBUS2
QVPS Bypass power switch
Rps\_on Drain-source on resistance

RX Receiver
SCL Serial clock
SDA Serial data

SIDO Single input dual output
SISO Single input single output
SMBus System management bus

TA Travel adapter TX Transmitter

USB Universal serial bus

### 2 References

[1] NXP Semiconductors N.V., UM10204 I<sup>2</sup>C-Bus Specification and User Manual, Revision 6, 201



# 3 Block Diagram

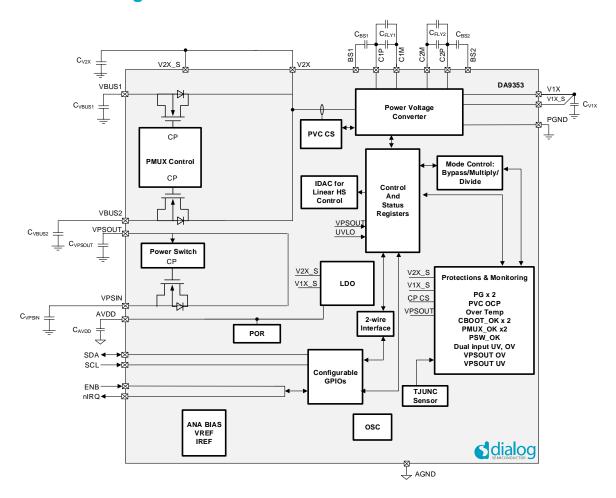


Figure 2: Block Diagram



**Pinout** 

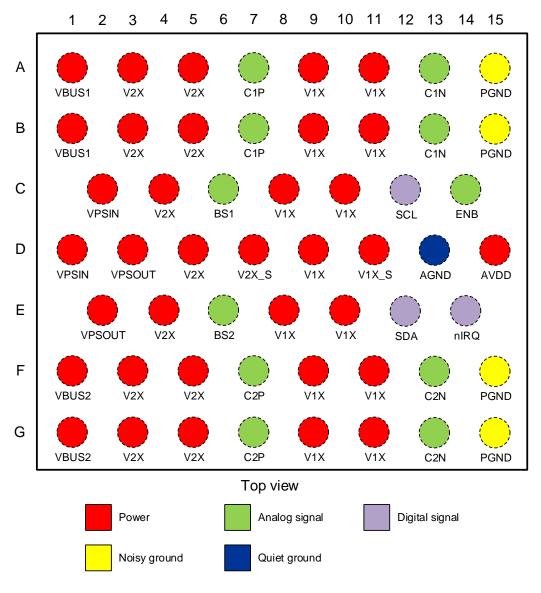


Figure 3: WLCSP Pinout Diagram (Top View)

**Table 1: Pin Description** 

WLCSP Pin #	Pin Name	Type (Table 2)	Description
A1, B1	VBUS1	PWR	Power mux. input/output 1
F1, G1	VBUS2	PWR	Power mux. input/output 2
D3, E2	VPSOUT	PWR	Power switch output
C2, D1	VPSIN	PWR	Power switch input
A3, A5, B3, B5, C4, D5 E4, F3, F5, G3, G5	V2X	PWR	Power supply
A7, B7	C1P	PWR	Flying capacitor 1 positive terminal



WLCSP Pin #	Pin Name	Type (Table 2)	Description
A13, B13	C1N	PWR	Flying capacitor 1 negative terminal
C6	BS1	DI	Bootstrap capacitor 1 positive terminal
C14	ENB	AIO	Enable (active low)
A9, A11, B9, B11, C8, C10, D9, E8, E10, F9, F11, G9, G11	V1X	PWR	Output voltage / power supply
E12	SDA	DIO	I <sup>2</sup> C data
E14	nIRQ	DO	nIRQ interrupt GPO
D7	V2X_S	Al	Power supply / output voltage sense
D11	V1X_S	Al	Output voltage / power supply sense
F7, G7	C2P	PWR	Flying capacitor 2 positive terminal
C12	SCL	DI	I <sup>2</sup> C clock
D15	AVDD	PWR	Power supply for internal logic and control
F13, G13	C2N	PWR	Flying capacitor 2 negative terminal
E6	BS2	PWR	Bootstrap capacitor 2 positive terminal
D13	AGND	GND	Analog quiet ground
A15, B15, F15, G15	PGND	GND	Power ground

# **Table 2: Pin Type Definition**

Pin Type	Description	Pin Type	Description
DI	Digital input	Al	Analog input
DO	Digital output	PWR	Power
DIO	Digital input/output	GND	Ground



### 4 Characteristics

### 4.1 Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

**Table 3: Absolute Maximum Ratings** 

Parameter	Description	Conditions	Min	Max	Unit
T <sub>STG</sub>	Storage temperature		-65	150	°C
TJ	Junction temperature		-40	150	°C
VVBUS2_LIM	Limiting voltage on VBUS2	Ramp < 0.1 V/μs	-0.3	24	V
VVBUS1_LIM	Limiting voltage on VBUS1	Ramp < 0.1 V/µs	-0.3	24	V
Vvpsout_lim	Limiting voltage on VPSOUT	Ramp < 0.1 V/μs	-0.3	24	V
Vvpsin_lim	Limiting voltage on VPSIN	Ramp < 0.1 V/μs	-0.3	24	V
V <sub>V2X_LIM</sub>	Limiting voltage on V2X	Ramp < 0.1 V/μs	-0.3	24	V
V <sub>V1X_LIM</sub>	Limiting voltage on V1X	Ramp < 0.1 V/μs	-0.3	16	V
V <sub>CFLY_DIFF</sub>	Flying capacitor differential voltage across C <sub>FLY1</sub> and C <sub>FLY2</sub>		-0.3	12	٧
VCBS_LIM	Limiting bootstrap voltage across C <sub>BS1</sub> and C <sub>BS2</sub>		-0.3	5.5	V
V <sub>A</sub> VDD_LIM	Limiting core voltage on AVDD		-0.3	5.5	V
V <sub>PIN</sub>	Limiting voltage on all pins except above		-0.3	V <sub>AVDD</sub> + 0.3	V

## 4.2 Recommended Operating Conditions

**Table 4: Recommended Operating Conditions** 

Parameter	Description	Conditions	Min	Тур	Max	Unit
TJ	Junction temperature		-40		+125	ů
TA	Ambient temperature		-40		+85	°C
V <sub>DD_</sub> HI	Input supply voltage range for the higher voltage rails	V2X, VBUS1 and VBUS2 in SWITCHING (Divide mode)	8		21	V
		V2X, VBUS1, and VBUS2 in BYPASS (Forward mode)	4		12	V
$V_{DD\_LO}$	Input supply voltage range for the lower voltage rails	V1X in BYPASS (Reverse mode)	3.5		12	V
		V1X in SWITCHING (Multiply mode)	3.5		10.5	V



IVPS_MAX	Maximum continuous current on power switch		3	А
Iv2x_max_byp	Maximum continuous current on V2X	BYPASS (Forward and Reverse modes)	3	А
Iv2x_max_mult	Maximum continuous current on V2X	SWITCHING (Multiply mode)	2	A
Iv2x_max_div	Maximum continuous current on V2X	SWITCHING (Divide mode)	2.5	A
IV1X_MAX_BYP	Maximum continuous current on V1X	BYPASS (Forward and Reverse modes)	3	А
IV1X_MAX_MULT	Maximum continuous current on V1X	SWITCHING (Multiply mode)	4	А
Iv1x_max_div	Maximum continuous current on V1X	SWITCHING (Divide modes)	4.5	A
IVBUSx_MAX_BYP	Maximum continuous current on VBUSx	BYPASS (Forward and Reverse modes)	3	А
I <sub>VBUSx_MAX_MUL</sub>	Maximum continuous current on VBUSx	SWITCHING (Multiply mode)	2	А
IVBUSx_MAX_DIV	Maximum continuous current on VBUSx	SWITCHING (Divide mode)	2.25	А

# 4.3 Electrostatic Discharge Ratings

**Table 5: Electrostatic Discharge Ratings** 

Parameter	Description	Conditions	Min	Тур	Max	Unit
ESDнвм	Maximum ESD protection	Human body model (HBM) All exposed pins	2000			٧
ESDcdm	Maximum ESD protection	Charged device model (CDM)	500			V

### 4.4 Electrical Characteristics

Unless otherwise noted, the following is valid for  $T_A$  = -40 °C to +85 °C and  $V_{V2X}$  = 16 V (SWITCHING state) or  $V_{V2X}$  = 5 V (BYPASS state). Refer to Table 50 for recommended external components.



# **4.4.1** Power Voltage Converter

**Table 6: Power Voltage Converter** 

Parameter	Description	Conditions	Min	Тур	Max	Unit
Electrical Pe	erformance					
V <sub>DD_HI_BYP</sub>	Input supply voltage range for the higher supply voltage rails	V2X, VBUS1, VBUS2 in BYPASS state (Forward mode)	4		12	V
V <sub>DD_HI_SW</sub>	Input supply voltage range for the higher supply voltage rails	V2X, VBUS1, and VBUS2 in SWITCHING state (Divide mode)	8		21	V
$V_{DD\_LO\_RBYP}$	Input supply voltage range for the lower voltage rail	V1X in BYPASS state (Reverse mode)	3.5		12	>
V <sub>DD_LO_SW</sub>	Input supply voltage range for the lower voltage rail	V1X in SWITCHING state (Multiply mode)	3.5		10.5	<b>V</b>
IQ_PWR_DWN	Quiescent current in POWERDOWN	ENB = high V <sub>V1</sub> x = 5 V		30		μΑ
IQ_STANDBY	Current consumption STANDBY	$ENB = low$ $V_{V2X} = 5 V$ $PVC\_EN = 0x0$		100		μA
IQ_BYP	Quiescent current in BYPASS	ENB = low PVC_EN = 0x1 Vv2x = 5 V = Vv1x = 5 V		2		mA
I <sub>Q_RBYP</sub>	Quiescent current in BYPASS state (Reverse mode)	ENB = low V <sub>V2X</sub> = V <sub>V1X</sub> = 5 V PVC_EN = 0x1		2		mA
lo_act	Quiescent current in SWITCHING state	ENB = low PVC_EN = 0x1 FSW = 0x2 (300 kHz) No load		6		mA
tmult_startu P	Start-up time in Multiply mode	Time measured from PVC_EN = 0x1 to SYS_STATUS = 0xF and DIRECTION_STATUS = 0x1. No load on VBUSx		4		ms
tdiv_startup	Start-up time in Divide mode	Time measured from PVC_EN = 0x1 to SYS_STATUS = 0xF and DIRECTION_STATUS = 0x0. No load on V1X		1		ms
tbyp_startup	Start-up time in Forward Bypass mode	Time measured from PVC_EN = 0x1 to SYS_STATUS = 0x5 and DIRECTION_STATUS = 0x0. No load on V1X		2		ms



Time measured from PVC_EN = 0x1 to SYS_STATUD   Start-up time for Reverse   SYS_STATUD = 0x1 to OIRCCTION STATUS = 0x1 to O	Parameter	Description	Conditions	Min	Тур	Max	Unit
tps. startup         Start-up time for Power Switch         EN_QVPS = 0x1 to QVPS_ON = 0x1 to QVPS_ON = 0x1 to QVPS_ON = 0x1         6         ms           toveus1_start         Start-up time for Power Switch         Time measured from EN_QVBUS1 = 0x1 to QVBUS1_ON = 0x1         6         ms           toveus2_start         Start-up time for Power Switch         Time measured from EN_QVBUS2 = 0x1 to QVBUS2 = 0x1 to QVBUS2_ON = 0x1         6         ms           fsw         PVC switching frequency         Fixed frequency mode         50         1000         kHz           fsw         PVC switching frequency         Fixed frequency mode         50         1000         kHz           fsw         Spread spectrum modulation frequency mode         50         1000         kHz           fsw_EMI         Spread spectrum modulation frequency mode         50         1000         kHz           fsw_EMI         Spread spectrum modulation frequency mode         50         1000         kHz           fsw_EMI         Spread spectrum modulation frequency mode         50         1000         kHz           fsw_EMI         Spread spectrum modulation frequency mode         50         100         16         %           fsw_EMI         Spread spectrum modulation frequency mode         50         100         100         100 <t< td=""><td></td><td></td><td>PVC_EN = 0x1 to SYS_STATUS = 0x5 and DIRECTION_STATUS = 0x1.</td><td></td><td>0.5</td><td></td><td>ms</td></t<>			PVC_EN = 0x1 to SYS_STATUS = 0x5 and DIRECTION_STATUS = 0x1.		0.5		ms
Covelus   STAR   Start-up time for Power   Switch   Sw	tps_startup		$EN_QVPS = 0x1 to$		6		ms
Total Roy   Switch   Switch			EN_QVBUS1 = 0x1 to		6		ms
Spread spectrum modulation frequency range   Spread Spr			EN_QVBUS2 = 0x1 to		6		ms
Frequency range   SPRÉAD_WIDTH   Frequency   Frequency range   SPRÉAD_WIDTH   Frequency   Frequency	fsw	PVC switching frequency	Fixed frequency mode	50		1000	kHz
Point_20V   Efficiency in SWITCHING state (Divide mode)   Content of the conte	fsw_emi			-16		16	%
$\begin{array}{llllllllllllllllllllllllllllllllllll$	η <sub>DIV_20V</sub>		C <sub>FLY</sub> = 2 x 22 μF (0603, 16V) C <sub>V1X</sub> = 4.7 μF		97.9		%
η <sub>ΜULT_10V</sub> Efficiency in SWITCHING state (Multiply mode) $C_{FLY} = 2 \times 22  \mu F$ (0603, 16V) $C_{V2X} = 4.7  \mu F$ $C_{O2X} = 4.7  \mu F$ $C_{O2X} = 4.7  \mu F$ $C_{O3X} = 2  A$ (on VBUS1 or VBUS2)97.9%η <sub>ΜULT_8V</sub> Efficiency in SWITCHING state (Multiply mode) $V_{V1X} = 8  V$ $C_{FLY} = 2 \times 22  \mu F$ (0603, 16V) $C_{V2X} = 4.7  \mu F$ $C_{O3X} = 2  A$ (on VBUS1 or VBUS2)97.7% $R_{ON_BYP_V2X}$ Total $R_{ON}$ in BYPASS state (Forward or Reverse modes), measured between V2X and V1X $V_{V2X} = V_{V1X} = 10  V$ 30 $m\Omega$ $R_{ON_QVBUS1}$ On resistance of QVBUS13045 $m\Omega$ $R_{ON_QVBUS2}$ On resistance of QVBUS23045 $m\Omega$	η <sub>DIV_16V</sub>		C <sub>FLY</sub> = 2 x 22 μF (0603, 16V) C <sub>V1X</sub> = 4.7 μF		97.7		%
$ η_{\text{MULT\_8V}}  \begin{array}{ll} \text{Efficiency in SWITCHING} \\ \text{state (Multiply mode)} \end{array}  \begin{array}{ll} C_{\text{FLY}} = 2 \times 22 \ \mu\text{F} \ (0603, 16V) \\ C_{\text{V2X}} = 4.7 \ \mu\text{F} \\ \text{Load} = 2 \ \text{A} \ (\text{on VBUS1 or VBUS2}) \end{array} \qquad 97.7 \qquad \% \\ $ $ \begin{array}{ll} \text{Ron\_BYP\_V2X} \\ \text{Ron\_QVBUS1} \end{array}  \begin{array}{ll} \text{Total Ron in BYPASS state} \\ \text{(Forward or Reverse modes), measured between V2X and V1X} \end{array}  V_{\text{V2X}} = V_{\text{V1X}} = 10 \ \text{V} \qquad 30 \qquad \text{m}Ω \\ \hline \begin{array}{ll} \text{Ron\_QVBUS1} \end{array}  \text{On resistance of QVBUS1} \qquad 30  45  \text{m}Ω \\ \hline \begin{array}{ll} \text{Ron\_QVBUS2} \end{array}  \text{On resistance of QVBUS2} \qquad 30  45  \text{m}Ω \\ \hline \end{array} $	ηмυιτ_10V		$C_{FLY} = 2 \times 22 \mu F (0603, 16V)$ $C_{V2X} = 4.7 \mu F$ Load = 2 A (on VBUS1 or		97.9		%
Ron_BYP_V2X       (Forward or Reverse modes), measured between V2X and V1X       VV2X = VV1X = 10 V       30 $mΩ$ Ron_QVBUS1       On resistance of QVBUS1       30       45 $mΩ$ Ron_QVBUS2       On resistance of QVBUS2       30       45 $mΩ$	ηм∪∟т_в∨		C <sub>FLY</sub> = 2 x 22 μF (0603, 16V) C <sub>V2X</sub> = 4.7 μF Load = 2 A (on VBUS1 or		97.7		%
Ron_QVBUS2 On resistance of QVBUS2 30 45 m $\Omega$	Ron_byp_v2x	(Forward or Reverse modes), measured between	V <sub>V2X</sub> = V <sub>V1X</sub> = 10 V		30		mΩ
	Ron_QVBUS1	On resistance of QVBUS1			30	45	mΩ
$R_{ON\_QVPS}$ On resistance of QVPS 22 33 $m\Omega$	Ron_QVBUS2	On resistance of QVBUS2			30	45	mΩ
	R <sub>ON_QVPS</sub>	On resistance of QVPS			22	33	mΩ



### 4.4.1.1 Efficiency Characteristics

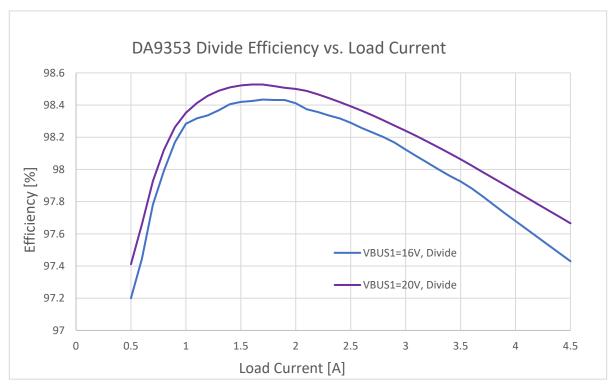
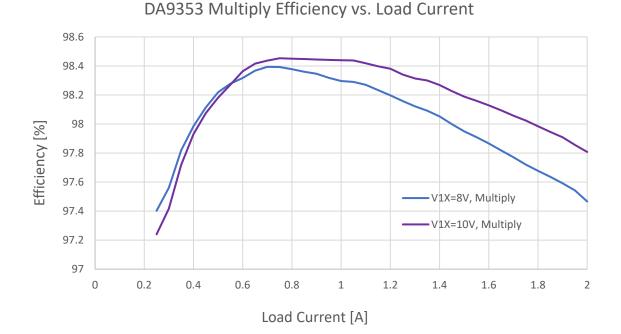


Figure 4: DA9353 Divide Mode Efficiency vs. Load Current, V2X

Conditions:  $C_{FLY1} = C_{FLY2} = 2 \text{ x } 22 \text{ } \mu\text{F}, C_{V1X} = 1 \text{ x } 4.7 \text{ } \mu\text{F}, f_{SW} = 300 \text{ kHz}$ 



Conditions:  $C_{FLY1} = C_{FLY2} = 2 \times 22 \mu F$ ,  $C_{V2X} = 1 \times 4.7 \mu F$ ,  $f_{SW} = 300 \text{ kHz}$ 

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Figure 5: DA9353 Multiply Mode Efficiency vs. Load Current, V1X



# 4.4.2 Power-on-Reset and Current Supervision

**Table 7: Power-on-Reset and Current Supervision** 

Parameter	Description	Conditions	Min	Тур	Max	Unit		
Electrical Pe	Electrical Performance							
VTHR_LWR_PO	Power-on-reset lower threshold	Measured @ AVDD V <sub>V2X</sub> / V <sub>V1X</sub> decreasing	2.1		2.7	<b>V</b>		
VTHR_UPPER_ POR	Power-on-reset upper threshold	Measured @ AVDD V <sub>V2X</sub> / V <sub>V1X</sub> increasing			2.8	٧		
Iv2x_pos_ocp _BYP	Positive peak current protection programmable range in BYPASS state (Forward mode)	Maximum current on V2X programmable via SEL_OCP_BYPASS (3.25, 3.5, 3.75, 4.0) A	3.25		4	А		
Iv2x_pos_ocp _sw	Positive peak current protection programmable range in SWITCHING state	Maximum current on V2X programmable via SEL_OCP (1.625, 2.125, 2.625, 3.125) A	1.625		3.125	Α		
Iv2x_neg_ocp _byp	Negative peak current protection programmable range in BYPASS state (Reverse mode)	Maximum current on V2X programmable via SEL_OCP_BYPASS (-3.25, -3.5, -3.75, -4.0) A	-4		-3.25	A		
Iv2x_neg_ocp _sw	Negative peak current protection programmable range in SWITCHING state	Maximum current on V2X programmable via SEL_OCP (-1.625, -2.125, -2.625,-3.125) A	-3.125		-1.625	A		
Iv2x_ocp_acc	Accuracy of current protection on HV rail	V <sub>V2X</sub> = 8 V OCP setting = 0x0 (3.25 A in BYPASS) OCP setting = 0x3 (3.125 A in SWITCHING)	-15		15	%		

# 4.4.3 Protections and Monitoring

**Table 8: Comparator Thresholds** 

Parameter	Description	Conditions	Min	Тур	Max	Unit
Electrical Performance						
VPSOUT_OV	Power switch over-voltage threshold limit on VPSOUT.	2-bit programmable via SEL_VPSOUT_OV (12, 13, 13.5, 14) V	12		14	٧
V <sub>P</sub> SOUT_UV	Power switch under-voltage threshold limit on VPSOUT.	2-bit programmable via SEL_VPSOUT_UV (3.2, 3.6, 4.0, 4.4) V	3.2		4.4	V



Parameter	Description	Conditions	Min	Тур	Max	Unit
VIN_OV_BYP_V BUSx	V <sub>IN</sub> over-voltage programmable range on VBUS1/VBUS2 (indirect protection through V2X) or V1X in BYPASS state	2-bit programmable via SEL_OVP (12, 13, 13.5, 14) V	12		14	V
V <sub>IN_OV_BYP</sub>	V <sub>IN</sub> over-voltage programmable range on V2X or V1X in BYPASS state	2-bit programmable via SEL_OVP (12, 13, 13.5, 14) V	12		14	V
VIN_OV_MUL	V <sub>IN</sub> over-voltage programmable range on V1X in SWITCHING (Multiply mode)	2-bit programmable via SEL_OVP_MULT (9.5, 10, 10.5, 11) V	9.5		11	V
Vin_ov_div_v busx	V <sub>IN</sub> over-voltage programmable range on VBUS1/VBUS2 (indirect protection through V2X) in SWITCHING (Divide mode)	2-bit programmable via SEL_OVP (19, 20, 21, 22) V	19		22	V
VIN_OV_DIV	V <sub>IN</sub> over-voltage programmable range on V2X in SWITCHING (Divide mode)	2-bit programmable via SEL_OVP (19, 20, 21, 22) V	19		22	V
V <sub>IN_OV_HYS</sub>	Input over-voltage hysteresis in SWITCHING	Falling hysteresis		750		mV
V <sub>IN_OV_HYS_B</sub> YP	Input over-voltage hysteresis in BYPASS	Falling hysteresis		950		mV
VIN_OV_DIV_B YP_ACC	Input over-voltage accuracy in SWITCHING (Divide mode) or BYPASS state	2-bit programmable via SEL_OVP	-3		3	%
VIN_OV_MUL_A	Input over-voltage accuracy in SWITCHING (Multiply mode)	2-bit programmable via SEL_OVP_MULT	-6		6	%
VIN_UV_BYP_M UL	V <sub>IN</sub> under-voltage on V2X in BYPASS state or V1X in SWITCHING (Multiply mode)	2-bit programmable via SEL_UV (3.2, 3.6, 4.0, 4.4) V, input voltage rising	3.2		4.4	V
VIN_UV_BYP_M UL_VBUSX	V <sub>IN</sub> under-voltage on VBUS1/VBUS2 in BYPASS state (indirect protection through V2X) or V1X in SWITCHING state (Mulitply mode)	2-bit programmable via SEL_UV (3.2, 3.6, 4.0, 4.4) V, input voltage rising	3.2		4.4	V
V <sub>IN_UV_DIV</sub>	V <sub>IN</sub> under-voltage on V2X in SWITCHING state (Divide mode)	2-bit programmable (7, 8, 9, 10) V, input voltage rising	7		10	V
VIN_UV_DIV_V BUSx	V <sub>IN</sub> under-voltage on VBUSx in SWITCHING state (Divide mode)	2-bit programmable (7, 8, 9, 10) V, input voltage rising	7		10	V



Parameter	Description	Conditions	Min	Тур	Max	Unit
VIN_UV_HYS	Input under-voltage hysteresis in SWITCHING (Divide mode)	Falling hysteresis		130		mV
VIN_UV_HYS_M UL_BYP	Input under-voltage hysteresis in Multiply mode or BYPASS	Falling hysteresis		200		mV
VIN_UV_ACC	Input under-voltage accuracy in SWITCHING (Divide or Multiply mode) and BYPASS state	2-bit programmable via SEL_UV	-3		3	%
V <sub>PG_NEG_</sub> SW	Power good negative switching programmable range Maximum allowed V1X - V2X/2 during SWITCHING state (Divide mode or Multiply mode)	V <sub>V1X</sub> = 8 V. 3 bit programmable via SELPG2. PVC in SWITCHING state (Mulitply mode)	100		450	mV
V <sub>PG_POS_</sub> SW	Power good positive switching programmable range Maximum allowed V2X/2 - V1X during SWITCHING state (Divide or Multiply mode)	V <sub>V2X</sub> = 16 V. 3 bit programmable via SELPG1. PVC in SWITCHING state (Divide mode)	100		450	mV
Vpg_neg_byp	Power good negative bypass programmable range Maximum allowed V1X - V2X during BYPASS (Forward or Reverse mode)	V <sub>V1X</sub> = V <sub>V2X</sub> = 5 V. 3 bit programmable via SELPG2. PVC in BYPASS state (Reverse mode)	100		450	mV
V <sub>PG_POS_BYP</sub>	Power good positive bypass programmable range Maximum allowed V2X - V1X during BYPASS (Forward or Reverse mode)	V <sub>V2X</sub> = V <sub>V1X</sub> = 5 V. 3-bit programmable with SELPG1 PVC in BYPASS state (Forward mode)	100		450	mV
Тот	Die over-temperature protection		140	145	150	°C
T <sub>OT_HYS</sub>	Die over-temperature protection hysteresis			10		°C
Vсвоот_ок	Voltage on bootstrap cap is OK to drive the power FET gate. Only used in non-switching states. In SWITCHING states this is automatically considered as OK.	BYPASS operation	2.7	3	3.6	V
VQVBUSx_OK	Voltage RCP FET is OK to drive the power FET gate.	Valid input detection for Power Mux operation	2.7	3	3.6	V
VQVPS_OK	Voltage on QVPS FET is OK to drive the power FET gate	Valid input detection for Power Mux operation	2.7	3	3.6	V

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# 4.4.4 Digital I/O Characteristics

## Table 9: Digital I/O Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit		
Electrical Pe	Electrical Performance							
ENB Pin								
VIH	Input high voltage		1.2			V		
VIL	Input low voltage				0.4	V		
V <sub>HYS</sub>	Hysteresis	Falling	-100			mV		
R <sub>PD_ENB</sub>	Internal pull down			100		kΩ		
SDA or SCL	SDA or SCL Pin							
VIH_SDA_SCL	Input high voltage SDA or SCL	Note 1	1.2			V		
VIL_SDA_SCL	Input low voltage SDA or SCL	Note 1			0.4	V		
SDA Pin								
Vol_sda	Output low voltage SDA	Open drain IouT_SDA = 3 mA			0.24	V		
nIRQ Pin	nIRQ Pin							
V <sub>OL_nIRQ</sub>	Output low voltage nIRQ	External pull-up resistor = 22 $k\Omega$			0.24	V		

Note 1 Input range compatible with 1.8 V and 3.3 V logic.



# 4.4.5 I<sup>2</sup>C Timing Characteristics

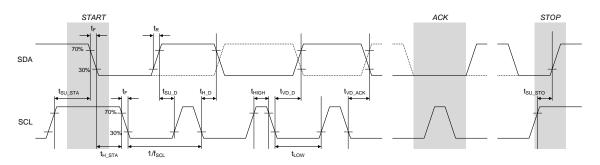


Figure 6: Interface Timing

**Table 10: I2C Timing Characteristics** 

Parameter	Description	Conditions	Min	Тур	Max	Unit		
Electrical Pe	Electrical Performance							
t <sub>BUF</sub>	Bus free time STOP to START		0.5			μs		
C <sub>BUS</sub>	Bus line capacitive load				150	pF		
fscL			0		1000	kHz		
tsetup_start	Start condition set-up time		0.26			μs		
thold_start	Start condition hold time		0.26			μs		
tLO_SCL	SCL low time		0.5			μs		
t <sub>HI_SCL</sub>	SCL high time		0.26			μs		
trise	I <sup>2</sup> C SCL and SDA rise time	(input requirement)			300	ns		
trall	I <sup>2</sup> C SCL and SDA fall time	(input requirement)			300	ns		
tsetup_data	Data set-up time		50			ns		
thold_data	Data hold time		0			ns		
tval_data	Data valid time				0.45	μs		
tval_data_ac	Data valid time acknowledge				0.45	μs		
tsetup_stop	Stop condition set-up time		0.26			μs		



# 5 Functional Description

### 5.1 System Architecture

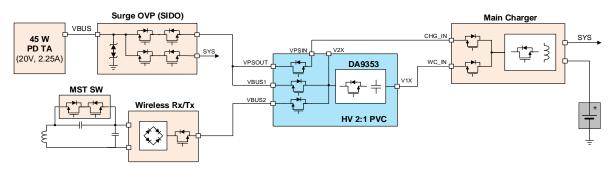


Figure 7: DA9353 Charging System Diagram 1

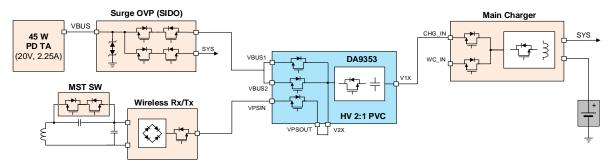


Figure 8: DA9353 Charging System Diagram 2

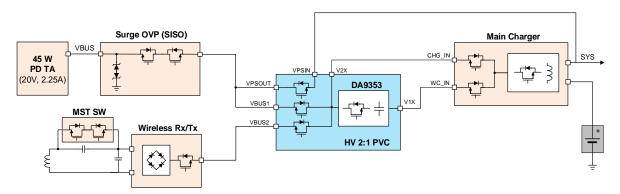


Figure 9: DA9353 Charging System Diagram 3

The system diagrams above illustrate configurations for the high voltage PVC with the inclusion of three internal power switches. These configurations enable the PVC to support a wide range of use cases depending on the application. Some use cases that the PVC is capable of supporting are:

- Dual power sharing: USB OTG (5 V) and wireless RX/TX; Charging System Diagram 1, see Figure 7.
- USB PD PPS TA (reduced R<sub>DS\_ON</sub> with parallel power switches) and HV TX; Charging System Diagram 2, see Figure 8.
- Bypass to SYS test mode support (no need for SIDO OVP); Charging System Diagram 3, see Figure 9.
- QVPS switch for providing power to gaming accessories



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### **Multi-Input Switched Capacitor Converter**

#### **5.1.1** Power Voltage Converter

The high voltage, high efficiency 2S to 1S PVC is capable of supplying multiple 1S voltage rails with up to 4.5 A output current, see Figure 10. The dual phase interleaved operation ensures an almost constant input current, resulting in improved immunity to noise.

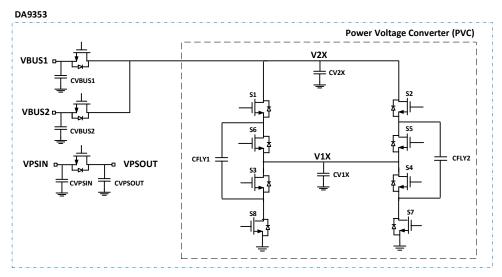


Figure 10: Power Voltage Converter Diagram

### 5.1.2 PVC Output Voltage

The PVC operates with a fixed duty cycle. Under no-load condition, the output voltage is half of the input voltage. When a current,  $I_{V1X}$ , is drawn at the V1X node and the PVC is switching at frequency of  $f_{SW}$ , the output voltage is determined as:

$$V_{V1X} = \frac{V_{V2X}}{2} - R_{EQ} \cdot I_{V1X}$$

#### Where:

REQ is a function of the sum of all resistances in the input/output power path (including the
power device's on-resistance and the PCB routing resistance) as well as the switching frequency,
CFLY, and PCB parasitics

The voltage ripple at  $V_{\text{OUT}}$  can be first order approximated as the voltage drop due to the discharge of the  $C_{\text{FLY}}$  capacitor in half of the period at an fsw switching frequency, plus the discharge voltage of the output capacitor during a typical 20 ns short dead time for phase switch.

#### 5.1.3 PVC Start-Up

DA9353 supports a PVC start-up into biased power rails (input and output). The PVC operation starts in current limited ramp up until the voltage between the high voltage port (V2X) and the low voltage port (V1X) is considered safe by the PVC's state machine, based on Power Good (PG) comparators. The duration of PVC start-up depends on the total effective capacitance connected to the PVC (flying capacitors and capacitance connected to the high and low voltage power ports) and the initial voltage deviation from the target ratio of 2:1 or 1:1. During PVC start-up, the PVC does not switch and the flying capacitors CFLY are connected in parallel to the output capacitor C<sub>V1X</sub>.

#### **NOTE**

To avoid overheating with thermal power cycling during PVC start-up it is the responsibility of the external application to limit load current from any of the power ports in correspondence to the OTP setting of the start-up current limit until PVC\_STATE is BYPASS or SWITCHING. At the end of the start-up phase the normal operation (BYPASS or SWITCHING) of the PVC is restored.



#### 5.1.4 DA9353 Power States

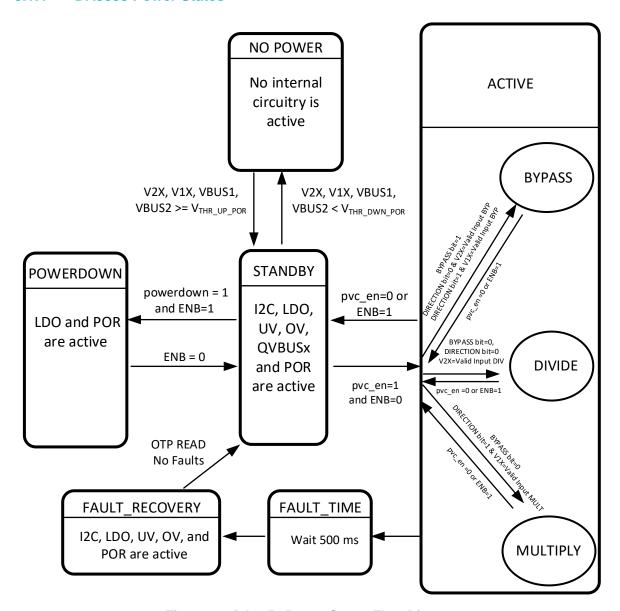


Figure 11: DA9353 Power States Flow Diagram

Note 1 Valid input BYPASS (Forward mode) = VIN\_UV\_BYP\_MUL < V2X < VIN\_OV\_BYP Valid input BYPASS (Reverse mode) = VIN\_UV\_BYP\_MUL < V1X < VIN\_OV\_BYP Valid input SWITCHING (Divide mode) = VIN\_UV\_DIV < V2X < VIN\_OV\_DIV Valid input SWITCHING (Multiply mode) = Same conditions as BYPASS

#### 5.1.5 NO POWER State

DA9353 is in NO POWER state when the input supply (V2X, V1X, VBUS1, VBUS2) is below the  $V_{THR\_LWR\_POR}$  threshold. During the NO POWER state, the supply voltage is too low for operation of the PVC and the Power-On Reset (POR) circuitry waits for sufficient input voltage.

When input supply ≥ V<sub>THR\_UPPER\_POR</sub> DA9353 transitions from NO POWER state into OTP load followed by ACTIVE or POWERDOWN state, depending on PVC\_EN setting.



#### 5.1.6 POWERDOWN State

The POWERDOWN state is the lowest quiescent current operating state with a valid input supply. It activates the internal AVDD LDO, POR and ENB supervision circuitry. During POWERDOWN state the PVC is off and the flying capacitors are discharged. DA9353 transitions from POWERDOWN to STANDBY if the voltage level at ENB changes from high to low.

#### 5.1.7 STANDBY State

In STANDBY state the PVC is off and other blocks are operational. The 6 MHz main oscillator can be on during this state and I<sup>2</sup>C is functional. Other circuitry available includes OV and UV protection comparators on both V2X and VPSOUT, nIRQ, event handler, and enabling of the power mux FETs.

STANDBY is also used to support application low power modes with lower quiescent current. This state can be entered into and exited with PVC\_EN register write or by driving ENB pin.

#### 5.1.8 FAULT TIME and FAULT RECOVERY States

When a fault turns off the PVC, DA9353 transitions from ACTIVE through FAULT TIME (500 ms) to FAULT RECOVERY.

Fault events are captured in the PVC\_EVENT (0x0022) and PVC\_EVENT\_B (0x0023) registers for host interrogation and generate maskable interrupt events. FAULT RECOVERY is a temporary state and is automatically entered and exited depending on fault condition presence.

The device waits for a FAULT TIME after the PVC is disabled. DA9353 automatically exits FAULT RECOVERY state when the fault condition has expired. The PVC\_EVENT and PVC\_EVENT\_B registers can be reset by a register write of 1 to the appropriate register bit.

#### **5.1.9 ACTIVE**

ACTIVE is the main operating state of DA9353. In this state, the PVC is on and operates in SWITCHING state (Divide or Multiply mode) or BYPASS state (Forward or Reverse mode). DA9353 exits out of the ACTIVE state in any of the following circumstances:

- the PVC is disabled (PVC\_EN = 0) or ENB = high
- the input supply is outside the supported range
- the junction temperature exceeds the critical threshold
- a fault has occurred

#### 5.1.9.1 SWITCHING State (Divide or Multiply Mode)

During SWITCHING state, any two of the PVC switches in one branch are turned fully on (for example S1 and S3) while the other two switches (in this case S6 and S8) are off, see Figure 10. This configuration occurs during one phase operation of the PVC. In the second phase, the polarity of these switches is reversed.

The PVC is switching between these two phases to place the flying capacitor in series or parallel to the V1X capacitor. The act of charging the capacitor in one phase and redistributing the charge to the V1X capacitor in the other phase enables the doubling or halving operation.

This is dependent on the direction of the configured PVC and input voltage applied (VBUSx or V1X). The PVC operates with two branches interleaved to reduce switching ripple and improve efficiency performance, see Figure 10.

There are two modes of operation in SWITCHING state (Divide or Multiply). The configuration of either of these modes is dependent on a valid input supply being applied (VBUSx or V1X) and the settings of the BYPASS and CHARGE\_DIRECTION register bits, see Table 11.

#### 5.1.9.2 BYPASS State (Forward or Reverse Mode)

In BYPASS, the PVC turns on the four switches (S1, S2, S5, and S6) on the high side and S7, S8 on the low side.  $V1X \approx V2X$  and both PG comparators are expected to be high.



The PVC will remain in Forward mode if the BYPASS register bit is asserted and CHARGE\_DIRECTION bit is de-asserted, see Table 11.

To operate in Reverse mode (when input voltage supply is applied on V1X), BYPASS and CHARGE DIRECTION bits should be set high.

**Table 11: PVC Operation Modes** 

Input Voltage Supply	BYPASS Bit	CHARGE_DIRECTION Bit	Operating Modes
VBUSx	0	0	Divide
V1X	0	1	Multiply
VBUSx	1	0	Forward
V1X	1	1	Reverse

#### 5.1.10 Power Mux and Power Switch Start-Up Scenarios

DA9353 supports autonomous startup on VBUS2, VPSOUT, and V2X. For the start-up configuration for each mode of operation see Table 12.

**Table 12: Start-Up Scenarios** 

Power Supply	Autonomous Start	Soft-Start Divide	Soft-Start BYPASS	Soft-Start Multiply
VBUS1	No	Yes (to V1X, not to V2X)	Yes (to V1X)	N/A
VBUS2	Yes	Yes (to V1X, not to V2X)	Yes (to V1X)	N/A
VPSOUT	Yes (BYPASS both modes)	N/A	Yes (to VPSIN)	N/A
VPSIN	No	N/A	Yes (diode to VPSOUT)	N/A
V2X	Yes (Forward mode only)	Yes	Yes	N/A
V1X	No	N/A	Yes (to VBUSx, not to V2X)	Yes (to VBUSx, V2X)

#### 5.1.11 Power Switch Control

The bypass power switch connected between VPSOUT and VPSIN (QVPS) will turn on autonomously when a valid voltage is present on VPSOUT. Likewise, QVPS will turn off when there is no valid voltage on VPSOUT, an over-temperature fault condition, or when EN\_QVPS is set to 0. A valid voltage on VPSOUT represents a voltage greater than VPSOUT\_UV and less than VPSOUT\_OV. The state of QVPS (Off, On, or Linear) is summarized in Table 13.

The QVPS power switch is activated when  $V_{PSOUT\_UV}$  (comparator output) is set to 0 (the voltage level of VPSOUT is greater than the  $V_{PSOUT\_UV}$  threshold). If this condition is met and EN\_QVPS is 1, then QVPS will be operating in either Linear or On state.

The condition of the state depends on whether QVPS\_SS\_TIMER (QVPS soft-switching timer) has expired or not. QVPS\_SS\_TIMER starts when all valid conditions are met to activate QVPS. If QVPS\_SS\_TIMER has not expired and EN\_QVPS is 1, then QVPS will be in the Linear state. Otherwise, QVPS will be operating in the On state once the timer has expired. The timer settings for QVPS can be adjusted from QVPS\_SS\_TIMER 2-bit register. It has programmable timer settings of 1 ms, 5 ms, 10 ms, and 20 ms, see Table 13.



#### **NOTE**

If QVPS is not required for the application then set  $EN_{QVPS} = 0x0$ ; in addition, connect VPSOUT and VPSIN to the ground planes on the PCB.

**Table 13: QVPS Power Switch Control** 

VPSOUT_UV	EN_QVPS	QVPS_SS_TIMER Expired	QVPS State
X	0	N/A	Off
1	1	N/A	Off
0	1	No	Linear
0	1	Yes	On

#### 5.1.12 Power Mux Control

Table 14: QVBUS1 and QVBUS2 Power Mux Control (VPSOUT PRIORITY = 0)

EN_QVBUSx	QVBUSx_SS_TIMER Expired	QVBUSx FET State
0	N/A	Off
1	No	Linear
1	Yes	On

Table 15 : QVBUS2 Only Power Mux Control (VPSOUT\_PRIORITY = 1)

EN_QVBUS2	VPSOUT_UV	QVBUS2_SS_TIMER Expired	QVBUS2 FET State
0	1	N/A	Off
1	1	No	Linear
1	1	Yes	On
X	0	N/A	Off

The state of QVBUSx (power mux FET) is governed by EN\_QVBUSx and QVBUSx\_SS\_TIMER expiration when VSPOUT\_PRIORITY = 0, see Table 14. If VPSOUT\_PRIORITY = 1, then QVBUS2 FET will not turn on if VPSOUT has a valid voltage present. This selection logic is available in DA9353 to enable autonomous turn-on for QVBUS2 and prevent the conduction of both switches (QVPS and QVBUS2) from turning on at the same time when a valid voltage is present on VPSOUT. In this scenario, QVPS will have the priority to turn on.

The condition for activating QVBUS2 FET with VPSOUT\_PRIORITY = 1, is dependent on EN\_QVBUS2, VPSOUT\_UV, and QVBUS2\_SS\_TIMER expiration, see Table 15.

QVBUS2 FET timer settings are programmable from a 2-bit register, VBUSx\_SS\_TIMER, with settings of 1 ms, 5 ms, 10 ms, and 20 ms.

## 5.2 Monitoring and Protections

Monitoring and Protections is a matrix of comparators for protecting the circuit from functioning in hazardous conditions and for controlling the state transitions.

### 5.2.1 Input Voltage Protection

Input voltage protection is used for detecting the presence of an input supply, VIN, and for disabling the PVC when VIN rises too high. The PVC is only operational when VIN (V2X or V1X) is within the range defined by [VIN\_UV\_BYP\_MUL or VIN\_UV\_DIV] and [VIN\_OV\_BYP, VIN\_OV\_MUL, or VIN\_OV\_DIV].



VIN over-voltage conditions will disable the PVC and will trigger OV\_FAULT\_EVENT. Resuming normal operation is allowed after all fault conditions are gone.

Similarly, under-voltage conditions will disable the PVC and will trigger UV\_FAULT\_EVENT. Resuming normal operation is allowed after all fault conditions are gone.

In DA9353, the feedback for the under-voltage and over-voltage comparators depends on the state and functional mode setting (CHARGE\_DIRECTION and BYPASS register bits) of the PVC. The feedback may either be taken on the V2X\_S or V1X\_S pin. Configuration for the feedback of these protection comparators is shown in Table 16.

Table 16: Input Selection for Under-Voltage and Over-Voltage Protection Comparators

CHARGE_DIRECTION Bit	BYPASS Bit	UV and OV Input	UV and OV Settings
0	1	V2X_S	BYPASS (Forward mode)
0	0	V2X_S	Divide
1	Х	V1X_S	BYPASS (Reverse mode) / Multiply

Note 1 If PVC is on, any change in CHARGE\_DIRECTION or BYPASS bits will not be registered until PVC turns off.

#### 5.2.2 Power Good Protection and Fault Generation

The purpose of the power good (PG) protection is to detect when the input-to-output voltage is within a safe operating window, defined by V<sub>PG\_NEG</sub> and V<sub>PG\_POS</sub> thresholds, see conditions for PG comparators (V<sub>PG\_NEG\_SW</sub>, V<sub>PG\_POS\_SW</sub>, V<sub>PG\_NEG\_BYP</sub>, V<sub>PG\_POS\_BYP</sub>) in .

DA9353 has two sets of PG comparators:

- PG\_NEG with V1X\_S positive input and V2X\_S negative input
- PG\_POS with V2X\_S positive input and V1X\_S negative input

Both comparators are used to detect a PG fault or to assist with start-up during the state transitions. Each comparator has OTP configuration settings and trimming capabilities.

The PG\_NEG and PG\_POS comparators output a 1 if the operating conditions on V2X\_S and V1X\_S are considered within safe limits for the PVC (ratio is less than the PG comparator threshold).

A PG fault is generated if at least one of the comparators outputs a 0 while the PVC is in BYPASS or SWITCHING state.

#### 5.2.3 Over-Current Protection

DA9353 features bi-directional current protection for protecting over-current in both forward and reverse direction. If a high current is sensed the OCP comparator will trigger a fault condition. The OCP comparator has 3-bit programmability for over-current selection for SWITCHING state, via bits SEL OCP, and another 3-bit setting for BYPASS state, via bits SEL OCP BYPASS.

#### NOTE

Do not configure SEL\_OCP\_BYPASS setting higher than 0x1. Settings above this value will exceed recommended current capability of the PVC.

#### 5.2.4 CFLY Short Protection

In addition to over-current protection, the PVC has a safety feature to protect the flying capacitors from being shorted. This generates a PG fault or OC fault.



#### 5.2.5 CBOOT\_OK Monitoring

During certain states (such as BYPASS) of the PVC's FSM, the bootstrap capacitors are being charged using an internal charge pump. The CBOOT\_OK comparators (1 and 2) are monitoring the voltage on the bootstrap capacitor. If enough voltage (3 V) is developed across the bootstrap capacitor, the comparator will set CBOOT\_OK = 1. The CBOOT\_OK signal ensures that high side power FETs are turned on with enough voltage gate drive.

A CBOOT\_OK fault is generated if CBOOT\_OK = 0 while the PVC is in BYPASS state. CBOOT\_OK fault will not be generated in any other PVC state, regardless of the CBOOT\_OK output.

#### 5.2.6 QVPS\_OK and QVBUSx\_OK Monitoring

When any of the three power FETs in the power mux are in the On or Linear state, the gate drive is charged using an internal charge pump. The QVPS\_OK and QVBUSx\_OK comparators monitor the gate-to-source voltages on these power FETs. If sufficient voltage is developed on the gate (3 V), the comparators will output a 1. These signals ensure that the power FETs are turned on with sufficient gate-source voltages.

A QVPS\_OK or QVBUSx\_OK fault is generated if the corresponding comparator = 0 while the power FET state is On. The fault will not be generated in any other power FET states (Off or Linear), regardless of the output of the comparator.

### **5.2.7** Over-Temperature Protection

DA9353 is protected from damage due to excessive power dissipation through thermal shutdown. There are two thresholds concerning thermal protection: thermal critical and thermal re-enable. When  $T_J$  is more than  $T_{OT}$  (thermal critical or over-temperature threshold), DA9353 enters FAULT state until  $T_J$  has dropped below  $T_{OT}$  -  $T_{OT}$  Hys (thermal re-enable threshold).

Due to the slow changing nature of  $T_J$ , a single comparator with an input hysteresis,  $T_{OT\_HYS}$ , is included. To reduce current consumption, the comparator is turned off during NO POWER and POWERDOWN states.

#### 5.2.8 PVC Timer Fault

This is a fault generated by the PVC's state machine whenever a transitional state timer expires before the condition to exit from that state. This will force the PVC to turn off instead of proceeding to the next state.

### 5.2.9 Watchdog Timer

DA9353 features a watchdog timer which monitors the host during its operation and disables the PVC if a timeout event occurs.

The watchdog timer is enabled, via I<sup>2</sup>C, through WD\_TIMER\_EN. If enabled, the timer is active in STANDBY (when both QVBUS1 and QVBUS2 are enabled) and in ACTIVE.

When enabled, the watchdog timer is loaded with a pre-programmed timeout period and starts decrementing. The timeout period value is selected, via I<sup>2</sup>C, in WD\_TIMER\_SEL.

When the watchdog timer is on, the host is expected to issue an I<sup>2</sup>C transaction to DA9353 before the end of the timeout period. The I<sup>2</sup>C transaction re-starts the watchdog timer by over-writing a new value to WD\_TIMER\_SEL.

However, if the host does not issue the transaction within the timeout period, and DISABLE\_WD\_TO\_EVENT is not set:

- 1. A timeout event occurs.
- 2. WD TO EVENT is asserted, unless masked by MASK WD TO EVENT.
- If the system is in ACTIVE state, the PVC is disabled and the system transitions to STANDBY.
- 4. In the system is in STANDBY state, QVBUS1 and QVBUS2 are disabled.
- 5. A watchdog timer fault is indicated by the WD\_TO\_STATUS bit.



#### NOTE

The registers bits WD\_TIMER\_SEL and WD\_TIMER\_EN are password protected. I<sup>2</sup>C access is required to unlock these bits. Write 0x3D to address 0xB541.

#### 5.2.10 nIRQ Fault

nIRQ is an active low, open drain output signal that indicates an interrupt has occurred. The related event and status information, such as warnings about temperature and voltages, over-current fault conditions, or status changes is available in the EVENT and STATUS registers.

The EVENT registers hold information about the events that have occurred. The conditions that are triggering the events are described in the individual event bit descriptions within the EVENT register tables, see Table 34 and Table 35. When an event bit is set the nIRQ signal is asserted, unless this event is masked by the appropriate MASK register.

The masked bits only mask the nIRQ assertion, and do not suppress the event generation. The nIRQ is not released until all event bits are cleared by writing a 1 to the appropriate EVENT register bits.

The assertion of the following conditions results in an nIRQ generation:

- VPSOUT\_UV\_OK
- QVBUS1 FAULT
- QVBUS2\_FAULT
- QVPS\_FAULT
- VPSOUT\_OV\_FAULT
- VPSOUT UV FAULT
- PG\_FAULT
- CBOOT\_FAULT

- OC\_FAULT
- OV FAULT
- UV\_FAULT
- OT\_FAULT
- CFLY\_SHORT\_FAULT
- CP\_TIMER\_FAULT
- SYS\_RESET
- WD\_TO\_EVENT

The following status or events prevent the PVC from turning on (in STANDBY state):

- QVBUS1\_FAULT\_STATUS
- QVBUS2\_FAULT\_STATUS
- UV\_STATUS
- WD\_TO\_STATUS

- OV\_STATUS
- OT\_STATUS
- AUTO\_FAULT\_RECOVERY

The following faults disable the PVC (in ACTIVE state):

- QVBUS1 FAULT STATUS
- QVBUS2\_FAULT\_STATUS
- UV STATUS
- OC\_STATUS
- OV\_STATUS
- WD\_TO\_STATUS

- OT STATUS
- PG\_FAULT\_STATUS
- CBOOT FAULT STATUS
- CFLY\_SHORT\_FAULT\_STATUS
- CP\_TIMER\_FAULT\_STATUS

The following faults disable the QVBUSx FETs (in STANDBY or ACTIVE state):

- OV\_FAULT\_STATUS
- WD\_TO\_STATUS

The following faults prevent QVPS FET from turning on:

- VPSOUT\_UV\_FAULT\_STATUS
- OT\_FAULT\_STATUS
- VPSOUT\_OV\_FAULT\_STATUS



#### 5.2.11 AVDD Internal Voltage Regulator

The AVDD supply is a 4 V rail internally generated by DA9353 for the internal analog and digital supply. It is always enabled except in NO POWER state.

AVDD is the only regulator with an external bypass capacitor at port AVDD. Power supplied for AVDD is derived from two possible power ports (V2X or V1X) via ports V2X\_S and V1X\_S. Depending on which voltage is higher, supply to the regulator rail is automatically switched. If the highest available voltage supplied for AVDD does not exceed V<sub>THR\_UPPER\_POR</sub>, DA9353 remains in a NO POWER state and no internal circuitry is active.

For V1X < 4.2 V and AVDD > V<sub>THR\_LWR\_POR</sub>, the LDO operates in dropout mode, to minimize quiescent current.

### 5.2.12 Low Power Operation

Low quiescent current operating modes are available in DA9353 for POWERDOWN, BYPASS (Forward and Reverse), and STANDBY states.

#### **NOTE**

When configuring the PVC for low quiescent current conditions, it is the responsibility of the application to ensure that the discharge FETs are not activated when the power mux or power switches are disabled.

Once activated, the PVC will draw additional current if there is a valid input voltage present at the travel adapter or wireless power input. If voltage is applied at V1X instead, there is no additional current drawn and the PVC operates in the low quiescent current setting. The conditions for activating a discharge FET is based on the power mux/switch being de-asserted, system is ready (STANDBY or ACTIVE state), and the discharge register bits are enabled. The register bits for controlling the appropriate discharge FETs are defined in PVC CTRL 2 register, see Table 32.

In addition to controlling the discharge FETs, the gate pulldowns on VBUS1 and VBUS2 must be set appropriately via PMUX3 register. If the gate pulldowns are enabled in POWERDOWN, the quiescent current will be high. To avoid this, the pulldowns must be disabled (DIS\_GATESTRPD\_VBUS1 and DIS\_GATESTRPD\_VBUS2 = 0x1) in POWERDOWN and enabled (DIS\_GATESTRPD\_VBUS1 and DIS\_GATESTRPD\_VBUS2 = 0x0) in any state other than POWERDOWN.



### 6 Control Interface

I<sup>2</sup>C is always enabled in ACTIVE or STANDBY and IOs run on AVDD.

DA9353 can be software controlled through an I<sup>2</sup>C serial control interface. Data are shifted into or out of DA9353 under the control of the host processor that also provides the serial clock. In a normal application case the interface is only configured once from OTP values, which are loaded during the initial start-up of DA9353. In this phase the I<sup>2</sup>C slave address is loaded from OTP.

#### 6.1 I<sup>2</sup>C Communication

DA9353 has an OTP configurable 7-bit I<sup>2</sup>C slave address (default: 0x70) which can be configured in the register field I2C\_SLAVE\_ADDRESS.

The SCL port functions as the I<sup>2</sup>C clock and the SDA port carries the bi-directional I<sup>2</sup>C data.

The  $I^2C$  interface is open drain supporting multiple devices on a single line. The bus lines have to be pulled high by external pull-up resistors (2 k $\Omega$  to 20 k $\Omega$  range). The devices connected to the  $I^2C$  SDA can only drive the bus line low to ground. As a result, two devices cannot conflict if they drive the bus simultaneously. The highest frequency of the bus is 1000 kHz. With asserted control  $I^2C_TIMEOUT_EN$  an automatic interface RESET can be triggered when the SDA and SCL signal ceases to toggle for > 35 ms (compatible with SMBus  $t_{TIMEOUT}$ ).

The interface supports an operation compatible with Standard-mode, Fast-mode, and Fast-mode Plus protocols, see I<sup>2</sup>C-Bus Specification Rev 6, [1].

The communication on the I<sup>2</sup>C bus always takes place between two devices, one acting as the master and the other as the slave. The DA9353 will only operate as a slave.

#### 6.2 I<sup>2</sup>C Control Bus Protocol

Data are transmitted over the  $I^2C$  bus in groups of eight bits. To send a bit the SDA line is driven to the intended state while the SCL is low (for example, a low on SDA indicates a zero bit). Once the SDA has settled the SCL line is brought high and then low. This pulse on SCL clocks the SDA bit into the receivers shift register.

DA9353 uses a 3-byte serial protocol which contains two bytes for the address and one byte for data. Data and address transfer is based on the MSB transmitted first for both read and write operations. All transmission begins with the START condition from the master as long as the bus is in IDLE state (the bus is free). The START condition is defined as a high to low transition at the SDA line while the SCL is high. The STOP condition is defined as a low to high transition at the SDA line while the SCL is high.



Figure 12: Timing of I<sup>2</sup>C START and STOP Condition

The I<sup>2</sup>C bus will be monitored by DA9353 for a valid SLAVE address whenever the interface is enabled. It responds immediately when it receives its own slave address. This acknowledge is done by pulling the SDA line low during the following clock cycle (white blocks marked with A in Figure 13 and Figure 14).

The protocol for a register write from master to slave consists of a START condition, a slave address with read/write bit and the 8-bit register address followed by 8 bits of data terminated by a STOP condition (all bytes responded to by DA9353 with Acknowledge):



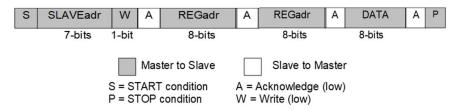


Figure 13: I<sup>2</sup>C Byte Write (SDA Line)

When the host reads data from a register it first has to write access DA9353 with the target register address and then read access DA9353 with a Repeated START or alternatively a second START condition. After receiving the data, the host sends No Acknowledge and terminates the transmission with a STOP condition:

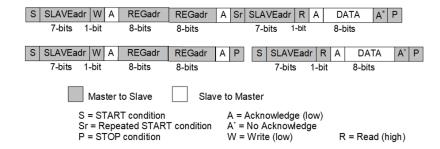


Figure 14: I<sup>2</sup>C Byte Read (SDA Line)



# **7** Register Definitions

# 7.1 Register Map

# Table 17: Register Map

Address	Register	Description
0x0002	STATUS_B	FSM and HW/SW modes
0x0003	REV_ID	Revision code
0x0004	VENDOR_ID	Specific vendor ID
0x0005	CONFIG_ID	Target application ID
0x000B	ONKEY_CONFIG_1	Auto fault recovery
0x000D	SYS_CONFIG_1	System configuration byte 1
0x000E	SYS_CONFIG_2	System configuration byte 2
0x0013	MASK_FAULT_CONFIG	Mask fault configuration byte 1
0x0014	MASK_FAULT_CONFIG_B	Mask fault configuration byte 2
0x0015	DISABLE_FAULT_CONFIG	Protection disable byte 1
0x0016	DISABLE_FAULT_CONFIG_B	Protection disable byte 2
0x0017	PVC_CONFIG	PVC configuration
0x0018	SYS_CTRL_1	System control byte 1
0x001C	PVC_CTRL_1	PVC control byte 1
0x001D	PVC_CTRL_2	PVC control byte 2
0x001F	SYS_STATUS	System Status byte 1
0x0022	PVC_EVENT	PVC event byte 1
0x0023	PVC_EVENT_B	PVC event byte 2
0x0024	PVC_STATUS	PVC status byte 1
0x0025	PVC_STATUS_B	PVC status byte 2
0x0026	PVC_STATUS_C	PVC status byte 3
0x0027	EVENT_LOG	Event logger
0x0039	I2C_SLAVE_ADDRESS	I2C communication slave address
0x0113	ANABIAS4	Analog bias byte 1
0x0114	ANABIAS5	Analog bias byte 2
0x0210	PROTECTION1	Protections byte 1
0x0311	PROTECTION10	Protections byte 2
0x0312	PROTECTION11	Protections byte 3
0x0511	PMUX2	Power mux. threshold settings for VPS switch
0x0512	PMUX3	Power mux gates disable settings

# Table 18: STATUS\_B (0x0002)

Bit	Mode	Symbol	Description	Reset
7:6	RO	RESERVED		0x0



Bit	Mode	Symbol	Description	Reset
5:2	RO	SYS_CTRL_STATE_READBACK	Readback Sys Ctrl FSM States 0: POWERDOWN 1: ACTIVE 2: FAULT_TIME 3: FAULT_RECOVERY 4:5 RESERVED 6: STANDBY 7:15 RESERVED	0x0
1:0	RO	RESERVED		0x0

## Table 19: REV\_ID (0x0003)

Bit	Mode	Symbol	Description	Reset
7:4	RO	MAJREV	Major revision code	0xA
3:0	RO	MINREV	Minor revision code	0xD

## Table 20: VENDOR\_ID (0x0004)

Bit	Mode	Symbol	Description	Reset
7:0	RO	VENDOR_ID	Specific Vendor ID	0x0
	OTP			

## Table 21: CONFIG\_ID (0x0005)

Bit	Mode	Symbol	Description	Reset
7:2	R/W OTP	CONFIG_ID	ID for customer and target application platform, written during production of variant (OTP variant)	0x0
1:0	R/W OTP	VARIANT_ID	Variant_ID (DA part number)	0x0

## Table 22: ONKEY\_CONFIG\_1 (0x000B)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	RESERVED		0x1
6	R/W OTP	AUTO_FAULT_RECOVERY	This bit determines the auto start of the PVC in case of previous faults.  Ox0: The host needs to clear all asserted events to allow the device to go back into ACTIVE state  Ox1: No host intervention is required. The device will re-enable itself if the faults go away. The events are still held.	0x1
5:4	R/W OTP	RESERVED		0x1
3:0	R/W OTP	RESERVED		0xD



# Table 23: SYS\_CONFIG\_1 (0x000D)

Bit	Mode	Symbol	Description	Reset
7:4	R/W OTP	RESERVED		0x1
3:1	R/W OTP	RESERVED		0x4
0	R/W OTP	VPSOUT_PRIORITY	This bit determines if autonomous startup on QVBUS2 is needed	0x0
			0x0: No autonomous startup on QVBUS2 0x1: Autonomous startup enable on QVBUS2. QVBUS2 can enable when VPSOUT_UV is high. When VPSOUT_UV goes low, QVBUS2 disables	

## Table 24: SYS\_CONFIG\_2 (0x000E)

Bit	Mode	Symbol	Description	Reset
7:6	R/W OTP	SPREAD_WIDTH	Spreading of oscillator frequency during spread spectrum  0x0: ±2 %  0x1: ±4 %  0x2: ±8 %  0x3: ±16 %	0x3
5	R/W OTP	SPREAD_EN	Spread spectrum enable 0x0: Off 0x1: On	0x0
4:3	R/W OTP	RESERVED		0x0
1:2	RWC OTP	WD_TIMER_SEL	Watchdog timer timeout period value 0x0: 5 s 0x1: 9 s 0x2: 17 s 0x3: 33 s	0x3
0	RWC OTP	WD_TIMER_EN	Watchdog timer enable 0x0: Disabled 0x1: Enabled	0x0

# Table 25: MASK\_FAULT\_CONFIG (0x0013)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	MASK_OV_FAULT	Mask the over-voltage fault 0x0: Mask disabled 0x1: Mask enabled	0x0
6	R/W OTP	MASK_UV_FAULT	Mask the under-voltage fault 0x0: Mask disabled 0x1: Mask OV fault enabled	0x0
5	R/W OTP	MASK_OT_FAULT	Mask the over-temperature fault 0x0: Mask disabled 0x1: Mask OT fault enabled	0x0
4	R/W	MASK_OC_FAULT	Mask the over-current fault	0x0



Bit	Mode	Symbol	Description	Reset
	OTP		0x0: Mask disabled	
			0x1: Mask OC fault enabled	
3	R/W	MASK_CBOOT_FAULT	Mask the CBOOT fault	0x0
	OTP		0x0: Mask disabled	
			0x1: Mask CBOOT fault enabled	
2	R/W	MASK_QVBUS1_FAULT	Mask the QVBUS1 fault	0x0
	OTP		0x0: Mask disabled	
			0x1: Mask QVBUS1 fault enabled	
1	R/W	MASK_QVBUS2_FAULT	Mask the QVBUS2 fault	0x0
	OTP		0x0: Mask disabled	
			0x1: Mask QVBUS2 fault enabled	
0	R/W	MASK_QVPS_OK	Mask the QVPS fault	0x0
	OTP		0x0: Mask disabled	
			0x1: Mask QVPS fault enabled	

## Table 26: MASK\_FAULT\_CONFIG\_B (0x0014)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	MASK_WD_TO_EVENT	Mask watchdog timeout event	0x0
6	R/W OTP	MASK_SYS_RESET_EVENT	Mask SYS_RESET event	0x0
5	R/W OTP	MASK_VPSOUT_UV_OK	Mask VPSOUT_UV_OK condition 0x0: Mask disabled 0x1: Mask VPSOUT_UV_OK event enabled	0x0
4	R/W OTP	MASK_VPSOUT_UV_FAULT	Mask VPSOUT_UV fault condition 0x0: Mask disabled 0x1: Mask VPSOUT_UV fault enabled	0x0
3	R/W OTP	MASK_VPSOUT_OV_FAULT	Mask VPSOUT_OV fault 0x0: Mask disabled 0x1: Mask VPSOUT_OV fault enabled	0x0
2:1	R/W OTP	RESERVED		0x0
0	R/W OTP	MASK_PG_FAULT	Mask PG fault 0x0: Mask disabled 0x1: Mask PG fault enabled	0x0

## Table 27: DISABLE\_FAULT\_CONFIG (0x0015)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	DISABLE_OV_FAULT	Disable OV fault	0x0
6	R/W OTP	DISABLE_UV_FAULT	Disable UV fault	0x0
5	R/W OTP	DISABLE_OT_FAULT	Disable OT fault	0x0
4	R/W OTP	DISABLE_OC_FAULT	Disable OC fault	0x0
3	R/W OTP	DISABLE_CBOOT_FAULT	Disable CBOOT fault	0x0
2	R/W OTP	DISABLE_QVBUS1_FAULT	Disable QVBUS1 fault	0x0
1	R/W OTP	DISABLE_QVBUS2_FAULT	Disable QVBUS2 fault	0x0
0	R/W OTP	DISABLE_QVPS_FAULT	Disable QVPS fault	0x0



# Table 28: DISABLE\_FAULT\_CONFIG\_B (0x0016)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	DISABLE_WD_TO_EVENT	Disable watchdog timeout fault	0x0
6:5	R/W OTP	RESERVED		0x0
4	R/W OTP	DISABLE_VPSOUT_OV_FAULT	Disable VPSOUT_OV fault	0x0
3	R/W OTP	DISABLE_VPSOUT_UV_FAULT	Disable VPSOUT_UV fault	0x0
2:1	R/W OTP	RESERVED		0x1
0	R/W OTP	DISABLE_PG_FAULT	Disable PG fault	0x0

## Table 29: PVC\_CONFIG (0x0017)

Bit	Mode	Symbol	Description	Reset
7:6	R/W OTP	RESERVED		0x3
5	R/W OTP	BYPASS	PVC BYPASS state 0x0: BYPASS state disabled 0x1: BYPASS state enabled	0x0
4	R/W OTP	PVC_EN	Enable or disable the PVC. 0x0: PVC disabled 0x1: PVC enabled	0x0
3:1	R/W OTP	FSW	Set the PVC switching frequency 0x0: 50 kHz 0x1: 200 kHz 0x2: 300 kHz 0x3: 375 kHz 0x4: 430 kHz 0x5: 600 kHz 0x6: 750 kHz 0x7: 1 MHz	0x2
0	R/W OTP	CHARGE_DIRECTION	0x0: Forward mode 0x1: Reverse mode	0x0

## Table 30: SYS\_CTRL\_1 (0x0018)

Bit	Mode	Symbol	Description	Reset
7:2	R/W	RESERVED		0x0
1	R/W	POWERDOWN	Forced POWERDOWN state when asserted from I <sup>2</sup> C write. Automatically cleared from wake-up	0x0
			0x0: POWERDOWN enabled	
			0x1: POWERDOWN not enabled	
0	R/W	SOFT_RESET	When asserted, triggers a power cycle and a reset of all internal registers, followed by an OTP download.	0x0
			Note: When the PVC is in Multiply mode (CHARGE_DIRECTION = Reverse mode and BYPASS = Disabled), DISABLE_OV_FAULT setting should be set to 0x1 before SOFT_RESET is asserted.	
			0x0: Not enabled	
			0x1: Enabled	



Table 31: PVC\_CTRL\_1 (0x001C)

Bit	Mode	Symbol	Description	Reset
7:6	R/W OTP	QVPS_SS_TIMER	Power switch soft start timer	0x1
			0x0: 1 ms	
			0x1: 6 ms	
			0x2: 12 ms	
			0x3: 24 ms	
5:4	R/W OTP	QVBUS1_SS_TIMER	PMUX soft start timer on QVBUS1	0x1
			0x0: 1 ms	
			0x1: 6 ms	
			0x2: 12 ms	
			0x3: 24 ms	
3:2	R/W OTP	QVBUS2_SS_TIMER	PMUX soft start timer on QVBUS2	0x1
		QVB002_00_THVIET	0x0: 1 ms	
			0x1: 6 ms	
			0x2: 12 ms	
			0x3: 24 ms	
1	R/W OTP	EN_VPSOUT_UV	This bit will enable the VPSOUT undervoltage comparator 0x0: Disabled 0x1: Enabled	0x1
0	R/W OTP	EN_VPSOUT_OV	This bit will enable the VPSOUT over-voltage comparator 0x0: Disabled	0x1
			0x1: Enabled	

### Table 32: PVC\_CTRL\_2 (0x001D)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	EN_QVPS	Enable for VPS power switch 0x0: Disabled 0x1: Enabled	0x0
6	R/W OTP	EN_QVBUS1	Enable for VBUS1 power switch 0x0: Disabled 0x1: Enabled	0x0
5	R/W OTP	EN_QVBUS2	Enable for VBUS2 power switch 0x0: Disabled 0x1: Enabled	0x0
4	R/W OTP	VPSIN_DISCH	VPSIN discharge 0x0: Disabled 0x1: Enabled	0x0
3	R/W OTP	RESERVED		0x0
2	R/W OTP	RESERVED		0x0
1	R/W OTP	V1X_DISCH_OVR_VALUE	V1X discharge override value. This bit is active when bit [0] is high 0x0: Disabled 0x1: Enabled	0x0



Bit	Mode	Symbol	Description	Reset
0	R/W OTP	V1X_DISCH_OVR_EN	V1X discharge override enable 0x0: Disabled 0x1: Enabled	0x0

### Table 33: SYS\_STATUS (0x001F)

Bit	Mode	Symbol	Description	Reset
7:4	RO	RESERVED		0x0
3:0	RO	PVC_STATE	Monitors the state of the PVC 0x0: PVC OFF 0x5: BYPASS 0xF: SWITCHING	0x0

### **Table 34: PVC\_EVENT (0x0022)**

Bit	Mode	Symbol	Description	Reset
7	RW1C	OV_FAULT_EVENT	Over-voltage event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
6	RW1C	UV_FAULT_EVENT	Under-voltage event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
5	RW1C	OT_FAULT_EVENT	Over-temperature event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
4	RW1C	OC_FAULT_EVENT	Over-current event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
3	RW1C	CBOOT_FAULT_EVENT	V <sub>CBSx</sub> voltage is not high enough to drive power FET gate 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
2	RW1C	QVBUS1_FAULT_EVENT	VBUS1 Power switch is not ready 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
1	RW1C	QVBUS2_FAULT_EVENT	VBUS2 Power switch is not ready 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
0	RW1C	QVPS_FAULT_EVENT	VPS power switch is not ready 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0

### Table 35: PVC\_EVENT\_B (0x0023)

Bit	Mode	Symbol	Description	Reset
7	RW1C	WD_TO_EVENT	Event to indicate that the watchdog timer has expired. This is a fault. Write a 1 to clear.	0x0



Bit	Mode	Symbol	Description	Reset
6	RW1C	SYS_RESET_EVENT	Event to indicate that the system has undergone a reset (POR or I2C triggered). This is not a fault.  0x0: No event has occurred	0x0
			0x1: Event has occurred. Write a 1 to clear	
5	RW1C	VPSOUT_UV_OK_EVENT	Event to indicate VPSOUT voltage is valid 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
4	RW1C	VPSOUT_UV_FAULT_EVENT	VPSOUT under-voltage event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
3	RW1C	VPSOUT_OV_FAULT_EVENT	VPSOUT over-voltage event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
2	RW1C	CP_TIMER _FAULT_EVENT	Indicates a charge pump timer fault event 0x0: No event has occurred 0x1: Event has occurred. Write a 1 to clear	0x0
1	RW1C	RESERVED		0x0
0	RW1C	PG_FAULT_EVENT	Power good signal fault in SWITCHING state (Multiply and Divide modes) or BYPASS state (Forward and Reverse modes). Write 0x1 to clear.  0x0: No event has occurred  0x1: Event has occurred	0x0

## Table 36: PVC\_STATUS (0x0024)

Bit	Mode	Symbol	Description	Reset
7	RO	OC_FAULT_STATUS	0x0: No fault 0x1: Indicates an over-current condition	0x0
6	RO	OV_FAULT_STATUS	0x0: No fault 0x1: Indicates an over-voltage condition	0x0
5	RO	UV_FAULT_STATUS	0x0: No fault 0x1: Indicates an under-voltage condition	0x0
4	RO	OT_FAULT_STATUS	0x0: No fault 0x1: Indicates an over-temperature condition	0x0
3	RO	CBOOT_FAULT_STATUS	0x0: No fault 0x1: Indicates CBOOT fault is active	0x0
2	RO	QVBUS1_FAULT_STATUS	0x0: No fault 0x1: Indicates QVBUS1 fault is active	0x0
1	RO	QVBUS2_FAULT_STATUS	0x0: No fault 0x1: Indicates QVBUS2 fault is active	0x0
0	RO	QVPS_FAULT_STATUS	0x0: No fault 0x1: Indicates QVPS fault is active	0x0



## Table 37: PVC\_STATUS\_B (0x0025)

Bit	Mode	Symbol	Description	Reset
7	RO	WD_TO_STATUS	A 1 on this indicates a VPSOUT undervoltage condition. This can be considered as a fault.	0x0
6:5	RO	RESERVED		0x0
4	RO	VPSOUT_UV_FAULT_STATU S	Indicates a VPSOUT under-voltage fault 0x0: No fault 0x1: Fault	0x0
3	RO	VPSOUT_OV_FAULT_STATU S	Indicates a VPSOUT over-voltage fault 0x0: No fault 0x1: Fault	0x0
2	RO	CP_TIMER_FAULT_STATUS	Indicates a PVC timeout fault 0x0: No fault 0x1: Fault	0x0
1	RO	RESERVED		0x0
0	RO	PG_FAULT_STATUS	Indicates a fault when the PVC is in SWITCHING state or in BYPASS state and at least one of the comparators is deasserted.  0x0: No fault  0x1: Fault	0x0

## Table 38: PVC\_STATUS\_C (0x0026)

Bit	Mode	Symbol	Description	Reset
7	RO	NIRQ	Reflects the status of the nIRQ pin (active low).	0x0
			0x0: IRQ is on 0x1: IRQ is off	
6	RO	RESERVED		0x0
5	RO	PVC_EN_STATUS	PVC enable (final control going to PVC) 0x0: PVC not enabled 0x1: PVC enabled	0x0
4	RO	SWITCHING_STATUS	Indicates if PVC is in 2:1 or 1:1 mode 0x0: BYPASS state 0x1: SWITCHING state (1:2 or 2:1)	0x0
3	RO	DIRECTION_STATUS	Indicates the direction of operation 0x0: Forward mode 0x1: Reverse mode	0x0
2	RO	QVPS_ON	Read out of raw analog signal 0x0: QVPS is not fully on 0x1: QVPS is on	0x0
1	RO	QVBUS1_ON	Read out of raw analog signal 0x0: QVBUS1 is not fully on 0x1: QVBUS1 is on	0x0
0	RO	QVBUS2_ON	Read out of raw analog signal	0x0



Bit	Mode	Symbol	Description	Reset
			0x0: QVBUS2 is not fully on	
			0x1: QVBUS2 is on	

#### **Table 39: EVENT\_LOG (0x0027)**

Bit	Mode	Symbol	Description	Reset
7:4	RO	RESERVED		0x0
3:0	RO	FIRST_EVENT_LOG	First event logger  0x0: N/A  0x1: CP_TIMER_EVENT  0x2: CFLY_SHORT_EVENT  0x3: OT_FAULT_EVENT  0x4: UV_FAULT_EVENT  0x5: OV_FAULT_EVENT  0x6: OC_FAULT_EVENT  0x7: CBOOT_OK_FAULT_EVENT  0x8: PG_FAULT_EVENT  0x9: VPSOUT_UV_FAULT_EVENT  0x10: VPSOUT_OV_FAULT_EVENT  0x11: QVPS_FAULT_EVENT  0x12: QVBUS2_FAULT_EVENT  0x14: WD_TIMEOUT_FAULT_EVENT  0x15: N/A	0x0

### Table 40: I2C\_SLAVE\_ADDR (0x0039)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	I2C_TIMEOUT_EN	Enable automatic reset of I2C interface (if SCL stays low for greater than 35 ms) 0x0: I2C timeout disabled 0x1: I2C timeout enabled	0x0
6:0	R/W OTP	I2C_SLAVE_ADDR	7-bit I2C slave address. Default is 7'h70. If user wants to change I2C slave ID, overwrite the I2C Slave ID as last register to program before OTP program so that other registers are not affected.	0x70

### Table 41: ANABIAS4 (0x0113)

Bit	Mode	Symbol	Description	Reset
7:5	R/W OTP	SEL_OCP	V2X over-current protection comparator threshold in SWITCHING state.	0x3
			0x0: 1625 mA	
			0x1: 2125 mA	
			0x2: 2625 mA	
			0x3: 3125 mA	
			0x4: Reserved	
			0x5: Reserved	
			0x6: Reserved	
			0x7: Reserved	



Bit	Mode	Symbol	Description	Reset
4:3	R/W OTP	RESERVED		0x2
2:0	R/W OTP	RESERVED		0x2

### Table 42: ANABIAS5 (0x0114)

Bit	Mode	Symbol	Description	Reset
7:3	R/W OTP	RESERVED		0x0
2:0	R/W OTP	SEL_OCP_BYPASS	V2X over-current protection comparator threshold in BYPASS state.  0x0: 3250 mA  0x1: 3500 mA  0x2: 3750 mA  0x3: 4000 mA  0x4: Reserved  0x5: Reserved  0x6: Reserved  0x7: Reserved	0x0

### Table 43: PROTECTION1 (0x0210)

Bit	Mode	Symbol	Description	Reset
7:5	R/W OTP	SELPG1	SELPG1 upper threshold selection (mV)	0x4
			0x0: 100	
			0x1: 150	
			0x2: 200	
			0x3: 250	
			0x4: 300	
			0x5: 350	
			0x6: 400	
			0x7: 450	
4:2	R/W OTP	SELPG2	SELPG2 lower threshold selection (mV)	0x4
			0x0: 100	
			0x1: 150	
			0x2: 200	
			0x3: 250	
			0x4: 300	
			0x5: 350	
			0x6: 400	
			0x7: 450	
1:0	R/W OTP	RESERVED		0x3

### Table 44: PROTECTION10 (0x0311)

Bit	Mode	Symbol	Description	Reset
7:6	R/W OTP	SEL_UV	Modifies the VREF2X threshold selection 0x0: V2X UVP = 7 V, V1X UVP = 3.2 V, BYPASS UVP = 3.2 V	0x0



Bit	Mode	Symbol	Description	Reset
			0x1: V2X UVP = 8 V, V1X UVP = 3.6 V, BYPASS UVP = 3.6 V	
			0x2: V2X UVP = 9 V, V1X UVP = 4 V, BYPASS UVP = 4 V	
			0x3: V2X UVP = 10 V, V1X UVP = 4.4 V, BYPASS UVP = 4.4 V	
5:0	R/W OTP	RESERVED		0x0

### Table 45: PROTECTION11 (0x0312)

Bit	Mode	Symbol	Description	Reset
7	R/W OTP	RESERVED		0x0
6:5	R/W OTP	SEL_OVP_MULT	Sets a voltage input level for the comparator in reverse direction  0x0: V1X OVP = 9.5 V  0x1: V1X OVP = 10 V  0x2: V1X OVP = 10.5 V  0x3: V1X OVP = 11 V	0x3
4:3	R/W OTP	SEL_OVP	Sets a voltage input level for the comparator in forward direction  0x0: V2X OVP = 19 V, V1X OVP = 12 V, BYPASS OVP = 12 V  0x1: V2X OVP = 20 V, V1X OVP = 13 V, BYPASS OVP = 13 V  0x2: V2X OVP = 21 V, V1X OVP = 13.5 V, BYPASS OVP = 13.5 V  0x3: V2X OVP = 22 V, V1X OVP = 14 V, BYPASS OVP = 14 V	0x3
2:0	R/W OTP	RESERVED		0x0

## Table 46: PMUX2 (0x0511)

Bit	Mode	Symbol	Description	Reset
7:4	R/W OTP	RESERVED		0x0
3:2	R/W OTP	SEL_VPSOUT_OV	Selects OV level for VPSOUT (V) 0: 12 1: 13 2: 13.5 3: 14	0x0
1:0	R/W OTP	SEL_VPSOUT_UV	Selects UV level for VPSOUT (V) 0: 3.2 1: 3.6 2. 4 3. 4.4	0x0

### Table 47: PMUX3 (0x0512)

В	it	Mode	Symbol	Description	Reset
7:	:4	R/W OTP	RESERVED		0x0



Bit	Mode	Symbol	Description	Reset
3	R/W OTP	DIS_GATESTRPD_VBUS1	Gate pull down control on VBUS1 0: Pull down is on 1: Pull down is off	0x0
2	R/W OTP	DIS_GATESTRPD_VBUS2	Gate pull down control on VBUS2 0: Pull down is on 1: Pull down is off	0x0
1:0	R/W OTP	RESERVED		0x0



# 8 Package Information

### 8.1 Package Outline

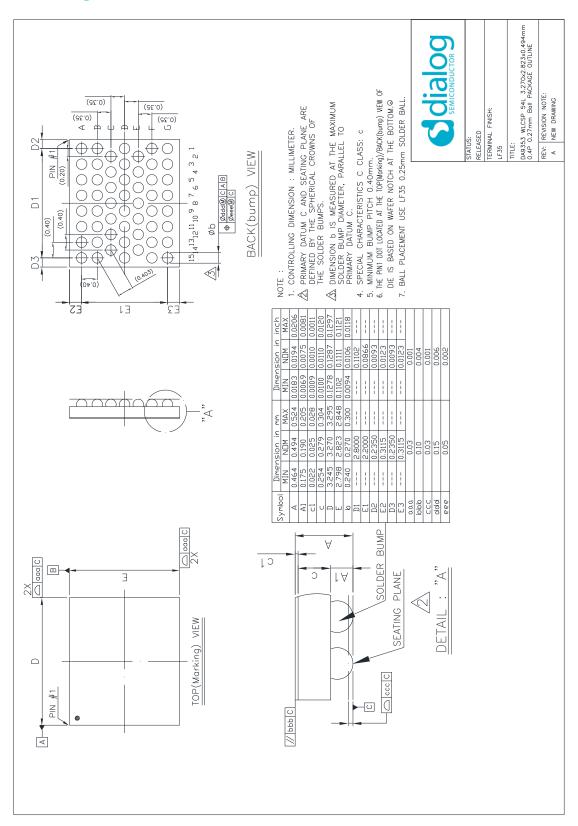


Figure 15: WLCSP Package Outline Drawing



#### 8.2 Moisture Sensitivity Level

The Moisture Sensitivity Level (MSL) is an indicator for the maximum allowable time period (floor lifetime) in which a moisture sensitive plastic device, once removed from the dry bag, can be exposed to an environment with a specified maximum temperature and a maximum relative humidity before the solder reflow process. The MSL classification is defined in Table 48.

For detailed information on MSL levels refer to the IPC/JEDEC standard J-STD-020, which can be downloaded from <a href="http://www.jedec.org">http://www.jedec.org</a>.

The WLCSP package is qualified for MSL 1.

**Table 48: MSL Classification** 

MSL Level	Floor Lifetime	Conditions
MSL 4	72 hours	30 °C / 60 % RH
MSL 3	168 hours	30 °C / 60 % RH
MSL 2A	4 weeks	30 °C / 60 % RH
MSL 2	1 year	30 °C / 60 % RH
MSL 1	Unlimited	30 °C / 85 % RH

#### 8.3 WLCSP Handling

Manual handling of WLCSP packages should be reduced to the absolute minimum. In cases where it is still necessary, a vacuum pick-up tool should be used. In extreme cases plastic tweezers could be used, but metal tweezers are not acceptable, since contact may easily damage the silicon chip.

Removal of a WLCSP package will cause damage to the solder balls. Therefore, a removed sample cannot be reused.

WLCSP packages are sensitive to visible and infrared light. Precautions should be taken to properly shield the chip in the final product.

#### 8.4 Soldering Information

Refer to the IPC/JEDEC standard J-STD-020 for relevant soldering information. This document can be downloaded from <a href="http://www.jedec.org">http://www.jedec.org</a>.



## 9 Ordering Information

The ordering number consists of the part number followed by a suffix indicating the packing method. For details and availability, please consult your Renesas local sales representative.

**Table 49: Ordering Information** 

Part Number	Package	Size (mm)	Shipment Form	Pack Quantity
DA9353-xxOV2	WLCSP54	3.270 x 2.823 x 0.494	Tape and reel	7500

#### Part Number Legend:

DA9353-xxOV2

xx: OTP variant

# 10 Application Information

#### 10.1 Recommended External Components

#### 10.1.1 Capacitor Selection

Use ceramic capacitors as bypass capacitors at all VDD and output rails. When selecting a capacitor, especially for types with high capacitance at smallest physical dimension, take the DC bias characteristic into account.

**Table 50: Recommended External Capacitors** 

Application	Value	Size	Tol (%)	Rated Voltage (V)	Туре
C <sub>FLY1</sub> , C <sub>FLY2</sub>	2 x 22 µF	0603	±20	16	Samsung CL10A226MO7JZNC
C <sub>V2X</sub>	4.7 µF	0603	±10	35	Murata GRM188R6YA475KE15
C <sub>V1X</sub>	4.7 µF	0603	±10	25	TDK C1608X5R1E475K080AC
Alternative C <sub>V1X</sub>	4.7 µF	0603	±20	16	Murata GRM188R61C475ME11
CVBUS1, CVBUS2, CVPSOUT, CVPSIN	1 μF	0402	±10	35	Murata GRM155R6YA105KE11
C <sub>BS1</sub> , C <sub>BS2</sub>	100 nF	0201	±10	16	Murata GRM033R61C104KE14D
CAVDD	2.2 µF	0402	±10	6.3	Murata GRM155R61C225KE11D



#### **Status Definitions**

Revision	Datasheet Status	Product Status	Definition
1. <n></n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may be changed in any manner without notice.
2. <n></n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterization data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
3. <n></n>	Final	Production	This datasheet contains the final specifications for products in volume production. The specifications may be changed at any time in order to improve the design, manufacturing, and supply. Major specification changes are communicated via Customer Product Notifications. Datasheet changes are communicated via <a href="https://www.renesas.com/">https://www.renesas.com/</a> .
4. <n></n>	Obsolete	Archived	This datasheet contains the specifications for discontinued products. The information is provided for reference only.

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